

Product Summary

BV _{DSS}	RDS(ON) Max	I _D Max T _C = +25°C
	8mΩ @ V _{GS} = 10V	70A
60V	12mΩ @ V _{GS} = 4.5V	50A

Description and Applications

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Engine Management Systems
- Body Control Electronics
- DCDC Converters

Features

- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching (UIS) Test in Production Ensures More Reliable and Robust End Application
- Low On-Resistance
- Low Input Capacitance
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMTH6010LK3Q is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/guality/product-definitions/

Mechanical Data

- Case: TO252
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.33 grams (Approximate)



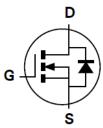
TO252 (DPAK)

Top View

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Pin Out Top View

Equivalent Circuit

Ordering Information (Note 4)

Part Number	Case	Packaging
DMTH6010LK3Q-13	TO252 (DPAK)	2,500/Tape & Reel

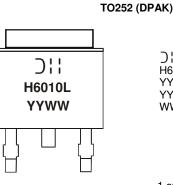
EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

Notes:



) | | = Manufacturer's Marking
H6010L = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 20 = 2020)
WW = Week Code (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage	VDSS	60	V		
Gate-Source Voltage	V _{GSS}	±20	V		
Continuous Drain Current, V _{GS} = 10V (Note 5)	Steady State	TA = +25°C TA = +70°C	ID	16.3 11.5	A
Continuous Drain Current, V _{GS} = 10V (Note 6) $T_{C} = +25^{\circ}C$ $T_{C} = +100^{\circ}C$			ID	70 50	A
Maximum Continuous Body Diode Forward Current (Note 6)			ls	60	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			ldм	280	А
Avalanche Current, L = 0.1mH			I _{AS}	20	A
Avalanche Energy, L = 0.1mH			Eas	20	mJ

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)	$T_A = +25^{\circ}C$	PD	3.1	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	Reja	47	°C/W
Total Power Dissipation (Note 6)	Tc = +25°C	PD	60	W
Thermal Resistance, Junction to Case (Note 6)	R _{eJC}	2.5	°C/W	
Operating and Storage Temperature Range	TJ, TSTG	-55 to +175	°C	

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)						*	
Drain-Source Breakdown Voltage	BVDSS	60	—	—	V	$V_{GS} = 0V, I_D = 1mA$	
			—	1	μA	$V_{DS} = 48V, V_{GS} = 0V$	
Zero Gate Voltage Drain Current (Note 8)	IDSS	_	—	100	μA	$V_{DS} = 48V, V_{GS} = 0V,$ $T_J = +125^{\circ}C$	
Gate-Source Leakage	lgss	_	—	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)						·	
Gate Threshold Voltage	V _{GS(TH)}	1	—	3	V	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	
Static Drain-Source On-Resistance		_	6.3	8	mΩ	V _{GS} = 10V, I _D = 20A	
Static Drain-Source On-Resistance	RDS(ON)	—	8.3	12	mΩ	$V_{GS} = 4.5V, I_D = 20A$	
Diode Forward Voltage	V _{SD}	_	0.9	1.2	V	V _{GS} = 0V, I _S = 20A	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss		2090	—		V _{DS} = 30V, V _{GS} = 0V, f = 1MHz	
Output Capacitance	Coss		746	—	pF		
Reverse Transfer Capacitance	Crss		38.5	—			
Gate Resistance	Rg	0.1	0.59	1.8	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Qg		19.3	—		V _{DS} = 30V, I _D = 20A	
Total Gate Charge (V _{GS} = 10V)	Qg	—	41.3	—	nC		
Gate-Source Charge	Qgs	_	6	—	no		
Gate-Drain Charge	Qgd	—	8.8	—			
Turn-On Delay Time	tD(ON)	_	5.7	—		V _{DD} = 30V, V _{GS} = 10V,	
Turn-On Rise Time	tR		4.3	_			
Turn-Off Delay Time	t _{D(OFF)}		23.4	—	ns	$I_D = 20A, R_g = 3\Omega$	
Turn-Off Fall Time	tF		9.7	_			
Body Diode Reverse Recovery Time	trr		35.4	_	ns		
Body Diode Reverse Recovery Charge	Q _{BB}	_	38.2	—	nC	I _F = 20A, di/dt = 100A/µs	

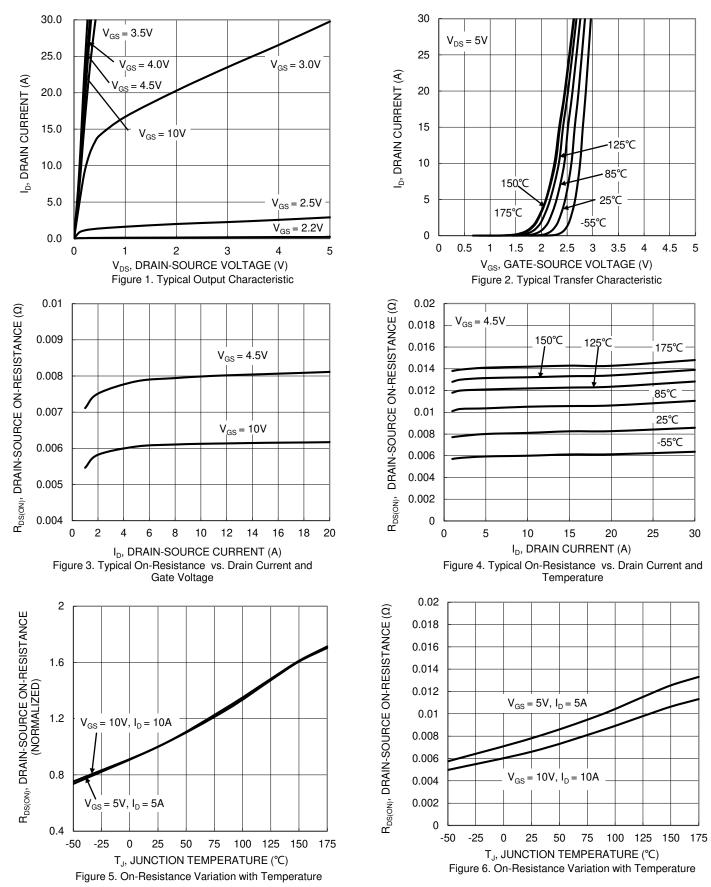
5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. Notes:

Thermal resistance from junction to soldering point (on the exposed drain pad).
Short duration pulse test used to minimize self-heating effect.

8. Guaranteed by design. Not subject to product testing.

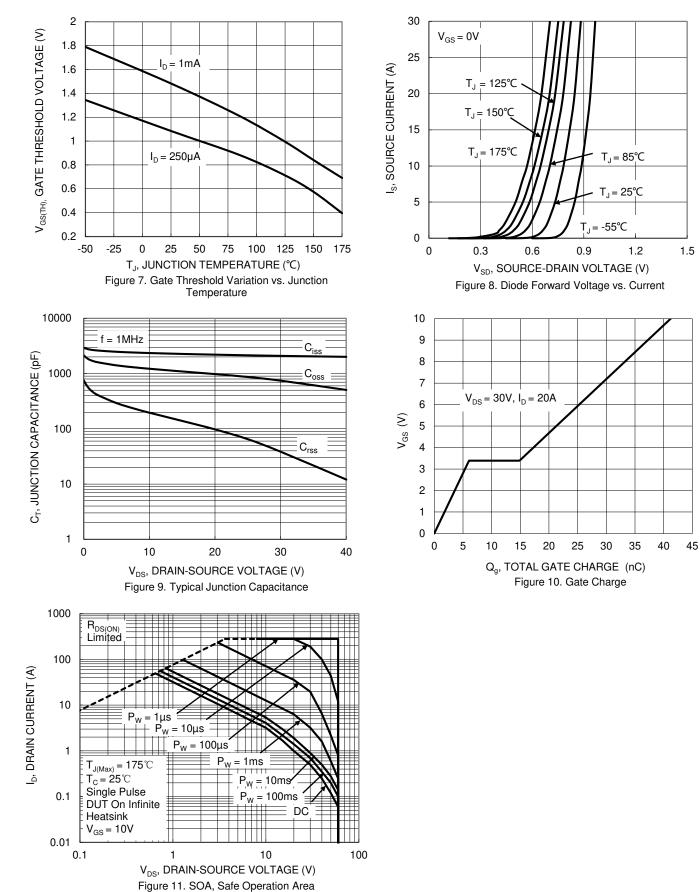


DMTH6010LK3Q





DMTH6010LK3Q



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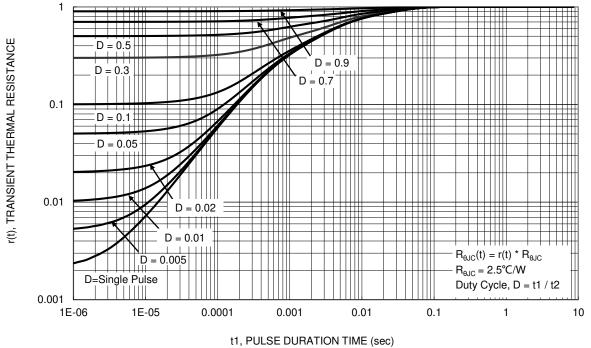
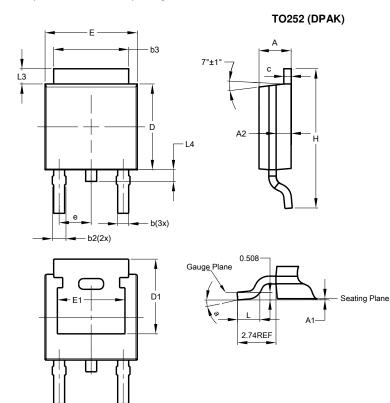


Figure 12 .Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

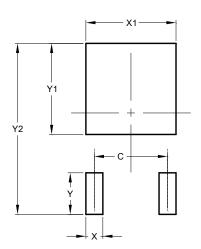


TO252 (DPAK)							
Dim	Min	Max	Тур				
Α	2.19	2.39	2.29				
A1	0.00	0.13	0.08				
A2	0.97	1.17	1.07				
b	0.64	0.88	0.783				
b2	0.76	1.14	0.95				
b3	5.21	5.46	5.33				
С	0.45	0.58	0.531				
D	6.00	6.20	6.10				
D1	5.21	-	-				
e	-	-	2.286				
Ш	6.45	6.70	6.58				
E1	4.32	-	-				
Η	9.40	10.41	9.91				
L	1.40	1.78	1.59				
L3	0.88	1.27	1.08				
L4	0.64	1.02	0.83				
а	0°	10°	-				
All	All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO252 (DPAK)



Dimensions	Value (in mm)			
С	4.572			
Х	1.060			
X1	5.632			
Y	2.600			
Y1	5.700			
Y2	10.700			



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